Abstract

An apparatus or system for handling and processing of substrates, more specifically electro-chemically active metal substrates, including a bath or dipping station having an autodepositable coating composition. In one embodiment, the apparatus is a square transfer apparatus having a plurality of stations including at least one metal pretreatment or cleaning station, and at least one autodepositable coating composition station. An operation as performed at each station is completed within a predetermined unit cycle time. A method for utilizing a square transfer apparatus including at least one step comprising coating a substrate with an autodepositable coating composition at an autodeposition station is disclosed.